



VACUUM APPLICATOR VA 724/N





DESCRIPTION

The Vacuum Applicator VA 724/N is a semi-automatic designed and built to ensure complete elimination of air from the surfaces of a printed circuit board, as well as perfect encapsulation of the traces. The machine has been developed for simultaneous application on both sides of the printed circuit panel of dry film, high conformation dry film solder mask ConforMASK™, and conventional dry film solder mask, or dielectric film and copper foil for SBU technology. In order to obtain perfect adhesion of the dry film and ensure total lack of air bubbles, VA 724/N employs heat, vacuum and pressure lamination.

ADVANTAGES

- Suitable for innerlayer or rigid panels full machine, range from 0.05–6.40 mm (0.002–0.250 in.) thickness
- Panel sizes up to 635 x 635 mm (25 x 25 in.)
- Entire platen area can be filled with one or more panels
- State-of-the-art vacuum technology
- Completely controlled by PLC—operator interface in local language
- Platen temperatures are individually controlled
- Suitable for clean room operations
- Convenient operator access
- Greatly reduces solder mask film waste

Overall Dimensions		Panel Size	
Width	1,270 mm (50.0 in.)	Width (max.)	635 mm (25.0 in.)
Length	1,800 mm (70.9 in.)	Length (max.)	635 mm (25.0 in.)
Height (min.–max.)	1,310–1,390 mm (51.6–54.7 in.)	Thickness (max.)	6.4 mm (0.252 in.)
Electrical Requirements		Working Height (Adjustment)	
Power Type	3 phase; 50/60 Hz + Ground	Working Height (min.–max.)	960–1,040 mm (37.8–40.9 in.)
Power Consumption	7.0 KVA		
Nominal Voltage*	400/480/220/200V ±7%		
Compressed Air			
Consumption	7 NI/min./cycle (0.25 CFM)		
Working Pressure	6 kg/cm (85.3 psi)		
Weight			
Gross	1,143 kg (2,519 lbs.)		
Net	970 kg (2,138 lbs.)		
*Different voltage can be provided upon requirement.			